

Wi-Fi*-ready MID Chip and Ceramic SMT Antennas

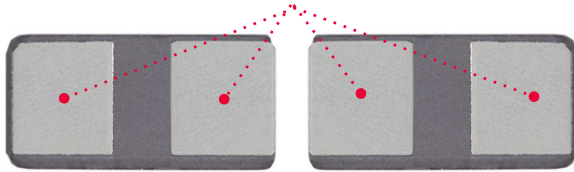


Ultra thin ceramic and LDS-MID antennas enable fast and easy integration into Wi-Fi devices for maximum performance at minimal implementation cost

Features and Benefits

Symmetrical radiator design

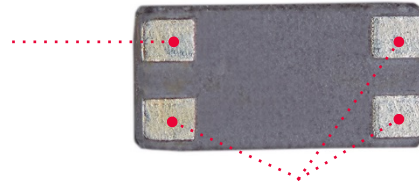
Offers significant design flexibility by allowing reversed lateral placement on the PCB without affecting radiation pattern or performance



The 2.4GHz SMT Ceramic Antenna with its symmetrical design maintain the same radiation pattern even when rotated 180 degrees to the horizontal

Feeding pad

Connects to the radio transceiver via a 50-Ohm transmission line on the PCB. Electrical signals from the transmission line are fed through this pad on the PCB



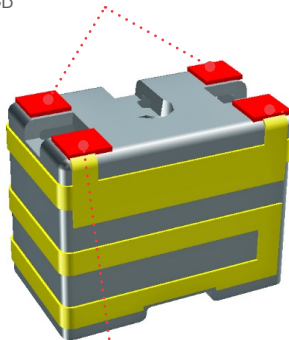
Grounding pad

Provides electrical grounding of antenna onto the application PCB

Underside view of the 2.4GHz SMT Ceramic Antenna showing Feeding and Ground Pads

(Dummy) Fixing pads

Firmly anchor antenna housing onto SMT pad of PCB



Grounding pad

Provides electrical grounding of antenna onto the application PCB

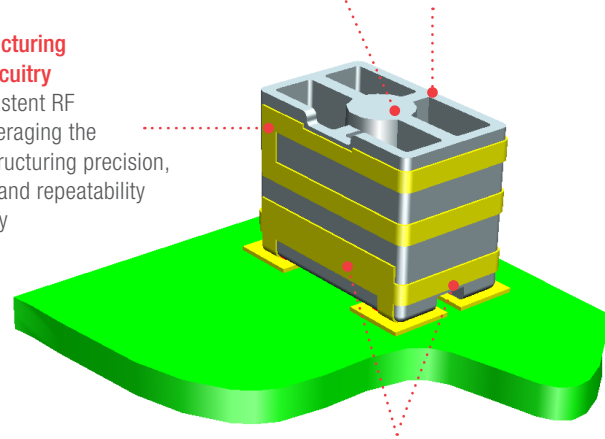
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2.4/5 GHz SMT MID Chip Antenna (Series 146175)

Laser Direct Structuring (LDS)-formed circuitry

Yields high, consistent RF performance, leveraging the excellent laser structuring precision, speed, accuracy and repeatability of LDS technology

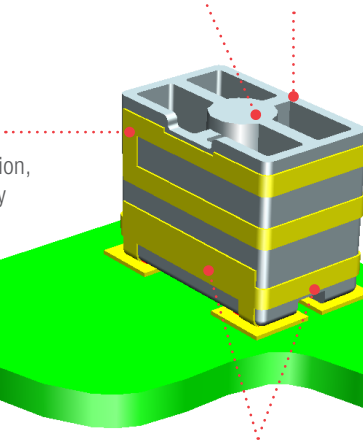


Halogen-free Molded Interconnect Device (MID) housing

Environmentally sustainable housing material withstands high reflow temperatures during assembly processing

Pick-and-place feature

Speeds up automated placement of antenna during assembly

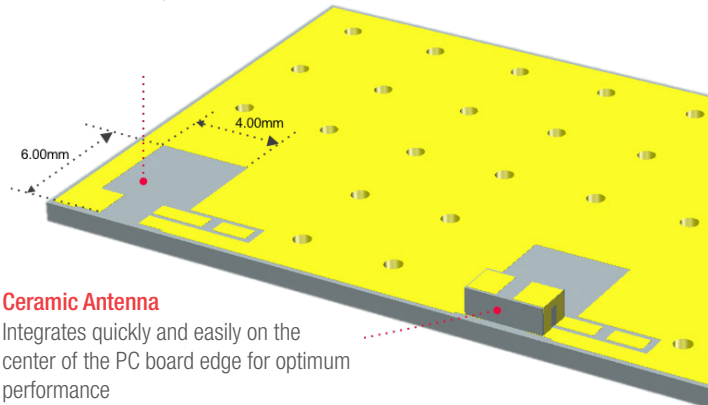


Gold (Au) over Nickel (Ni) traces

Act as transducers that convert unguided electromagnetic waves to guided electromagnetic waves and vice versa

Clearance Zone

Ensures little or no EMI interference from neighboring electronic components affecting antenna performance



Reference PCB layout of the 2.4GHz SMT Ceramic Antenna (Refer to AS-203006-001 for more information)

*Wi-Fi is a registered trademark of the Wi-Fi Alliance.

Remark: The above antennas support Bluetooth[®], ZIGBEE[®] and ISM (Industrial, Scientific and Medical) frequency bands

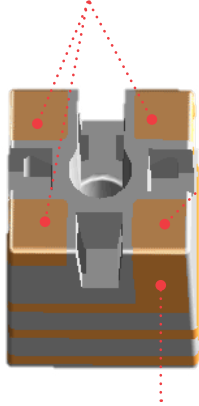
[®]Bluetooth is a registered trademark of Bluetooth SIG[®]ZIGBEE is a registered trademark of trademark of ZigBee Alliance

Wi-Fi*-ready MID Chip and Ceramic SMT Antennas



(Dummy) Fixing pads

Firmly anchors antenna housing onto SMT pad of PCB



Feeding pad

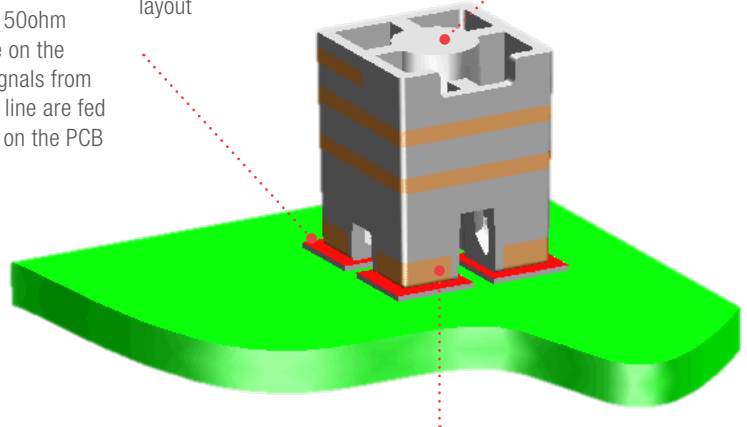
Connects to the radio transceiver via a 50ohm transmission line on the PCB. Electrical signals from the transmission line are fed through this pad on the PCB

Footprint for soldering on PCB

Facilitates PCB layout

Pick-and-place feature

Speeds up automated placement of antenna during assembly



Gold (Au) over Nickel (Ni) radiator traces

Act as transducers that convert unguided electromagnetic waves to guided electromagnetic waves and vice versa

Halogen-free Molded Interconnect Device (MID) housing

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Applications

Connected Home

- Security and Surveillance
- Home Automation
- Home Streaming
- Entertainment
- Smart Appliances
- Energy and Utilities

Wireless Infrastructure

- Wireless Solutions

Telecommunications/Networking

- Infrastructure/Networking

Commercial Vehicles

- Networking

2.4GHz SMT MID Chip Antenna (Series 47948)

Specifications

REFERENCE INFORMATION

Packaging: Tape on reel
 Reference Platform: 100.00 by 40.00 by 1.00mm (47948, 146175); 40.00 by 20.00 by 1.00mm (203006)
 Designed In: mm
 RoHS: Yes
 Halogen Free: Yes
 Ground Clearance:
 6.00 by 4.00mm (146175, 203006)
 4.00 by 4.00mm (47948)
 SMT Compatible: Yes

ELECTRICAL

RF Power (Watt): 2
 Return Loss - S11(dB): <-7 (47948); <-6 (146175); <-10 (203006)
 Average Total Radiation Efficiency(%):
 Refer to Product Specifications
 Peak Gain (dBi): Refer to Product Specifications
 Input Impedance (ohms): 50

MECHANICAL

Refer to Product Specifications

PHYSICAL

Housing: LCP-LDS, Vectra E840ILDS, 40% mineral-filled LDS grade (47948, 146175); Ceramic (203006)
 Flammability: UL 94V-0
 Plating:
 Operating Temperature: -40 to 125°C

Ordering Information

Series No.	Frequency Band (MHz)	Dimensions (mm)
203006	2400 to 2483.5	3.20(L) by 1.60(W) by 1.10(H)
146175	2400 to 2483.5 5150 to 5850	5.00(L) by 3.00(W) by 4.00 (H)
47948	2400 to 2483.5	3.00(L) by 3.00(W) by 4.00 (H)

www.molex.com/link/standard_antennas.html